



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

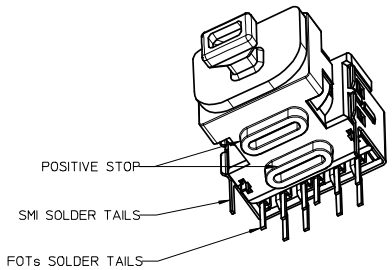
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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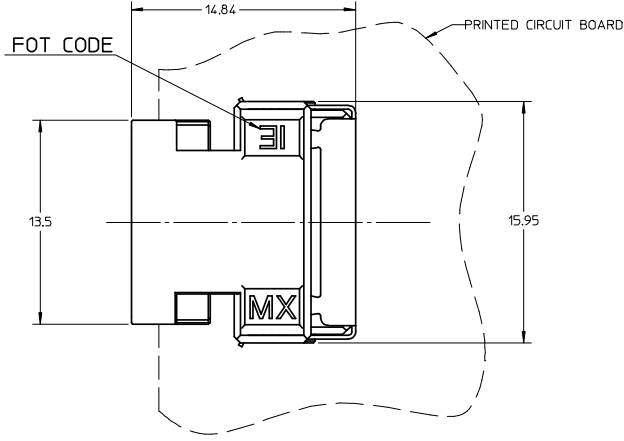
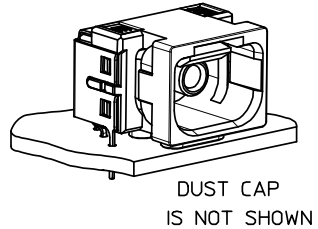
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



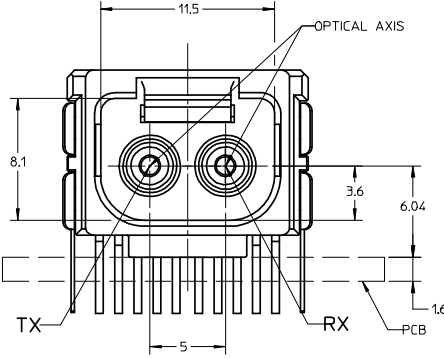
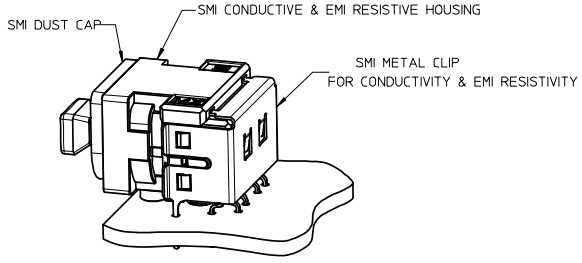
SMI/SMT TRANSCEIVER ASSEMBLY P/N	FOT's TYPE	FOT CODE
1061082100	IEEE-1394/ DIGITAL FDL300K	IE
1061083100	10/100 ETHERNET EDL300K	EL
1061084100	INDUSTRIAL DATA LINK IDL300K	ID



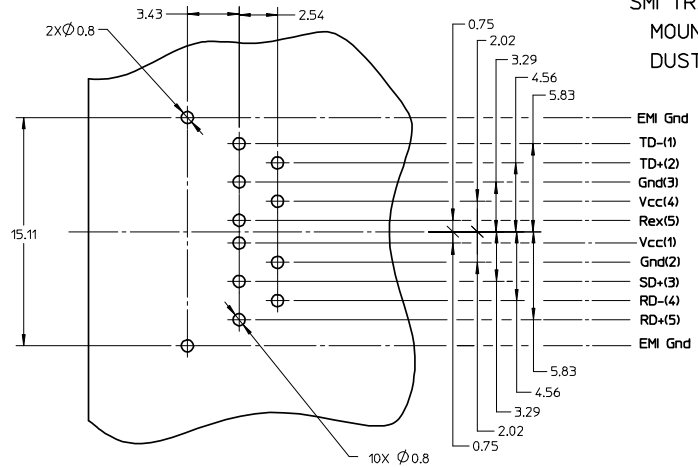
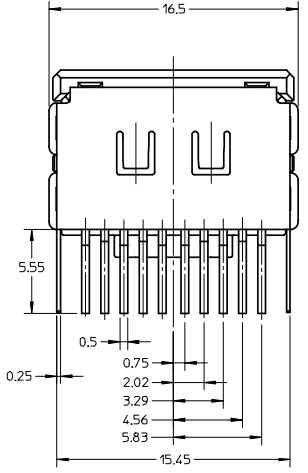
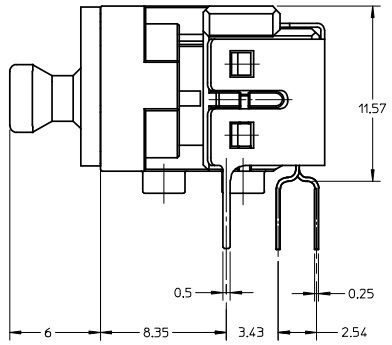
ISOMETRIC VIEWS
SCALE 2.5:1



DUST CAP NOT SHOWN



SMI TRANSCEIVER ASSEMBLY
MOUNTED ON THE PCB
DUST CAP NOT SHOWN



RECOMMENDED PCB LAYOUT
DIMENSIONS TOLERANCE: ±0.1mm

- NOTES:
- ALL DIMENSIONS ARE FOR REFERENCE ONLY EXCEPT FOR RECOMMENDED PCB LAYOUT.
 - ATTACHMENT OF THIS COMPONENT TO THE PCB VIA HOT BAR/LASER OR IR SOLDERING. RE-FLOW OVEN SOLDERING IS NOT APPROVED AT THIS TIME.

ENTER DESCRIPTION EC NO: MF2008-0555 DRWNS:SMIGO 2008/06/11 CHKD: 2008/06/11 APPR:SMIGO 2008/06/26	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		mm	INCH	DRAWN BY	DATE	TITLE SMI TRANSCEIVER ASSEMBLY THROUGH- HOLE SOLDERING			
REV B	DESCRIPTION	4 PLACES ±	±	BG	09/12/06	MOLEX INCORPORATED SD-106108-X100			
		3 PLACES ±	±	CHECKED BY	DATE				
		2 PLACES ±	±	SE	9/15/06	SHEET NO. 1 OF 1			
		1 PLACE ±	±	APPROVED BY	DATE				
		ANGULAR ±1/2°		MATERIAL NO.		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE					